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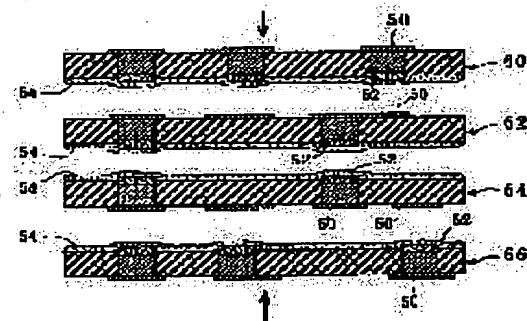
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 (22)Date of filing : 25.06.1999 (72)Inventor : ENOMOTO AKIRA
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(54) MULTILAYER PRINTED WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a multilayer printed wiring board exhibiting a low inner residual stress after laminating by thermal pressing by reducing elastic deformation and plastic deformation of insulating bases comprising the multilayer printed wiring board.

SOLUTION: A plurality of circuit boards having conductor circuits 50 on one side or both sides of its insulating substrate and via holes which electrically connect the conductor circuits 50 through the insulating substrate are layered and integrated by thermal press to form the multilayer printed wiring board. In this case, the insulating substrate is formed of glass fabric epoxy resin substrate 20-800 μm thick and contains 60-90 wt.% of glass fabric and SiO₂ base filler.



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